Unit: mm

TOSHIBA Diode Silicon Epitaxial Schottky Barrier Type

# DSF521CT

## **High Speed Switching Application**

Low forward voltage :  $V_{F(3)} = 0.5V$  (max)

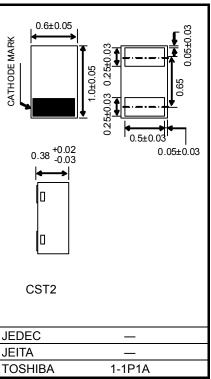
### Abusolute Maximum Ratings (Ta = 25°C)

Characteristic	Symbol	Rating	Unit	
Reverse voltage	$V_{R}$	30	V	
Maximum (peak) forward current	I <sub>FM</sub>	300	mA	
Average forward current	Io	200	mA	
Surge current (10ms)	I <sub>FSM</sub>	1	Α	
Power dissipation	P*	150	mW	
Junction temperature	Tj	125	°C	
Storage temperature range	T <sub>stg</sub>	−55 to 125	°C	
Operating temperature range	T <sub>opr</sub>	-40 to 100	°C	

<sup>\*:</sup> Mounted on a glass epoxy circuit board of 20 mm × 20 mm, pad dimension of 4 mm × 4 mm.

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).



Weight: 0.7 mg (typ.)

## **Electrical Characteristics (Ta = 25°C)**

Characteristic	Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
Forward voltage	V <sub>F (1)</sub>	_	I <sub>F</sub> = 1mA	_	0.2	_	V
	V <sub>F (2)</sub>	_	I <sub>F</sub> = 5mA	_	0.24	-	
	V <sub>F (3)</sub>	_	I <sub>F</sub> = 200mA	_	0.45	0.5	
Reverse current	I <sub>R (1)</sub>	_	V <sub>R</sub> = 10V	_	_	20	μА
	I <sub>R (2)</sub>	_	V <sub>R</sub> = 30V	_	_	30	
Total capacitance	C <sub>T</sub>	_	V <sub>R</sub> = 0, f = 1 MHz	_	34	_	pF

#### **Equivalent Circuit (top view)**



## Marking



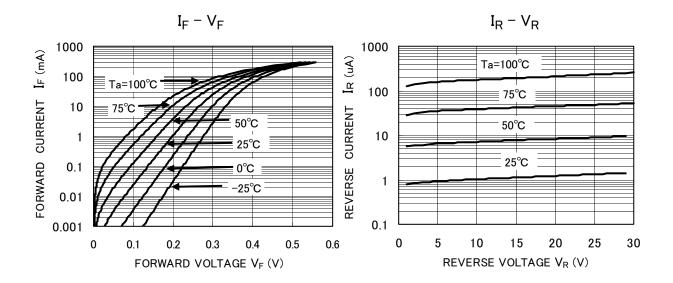
## **Handling Precaution**

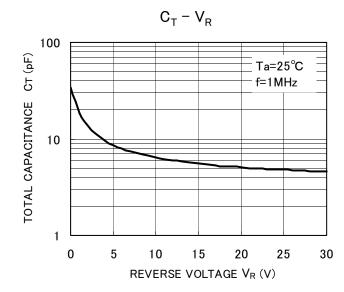
Schottky barrier diodes have reverse current characteristic compared to the other diodes.

There is a possibility SBD may cause thermal runaway when it is used under high temperature or high voltage.

Please take forward and reverse loss into consideration during design.

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